

MFS RIGID-FLEX

MANUAL FLEX SYSTEM

Member of the

DATAALIGN™
SERIES OF EQUIPMENT



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DIS has developed a series of registration bonding systems to process all types of multilayer PCB's including Rigid, Rigid-Flex and Flex circuit boards. The MFS is a manually operated system that assists manufacturers during the pin lay-up process. The unique design of the MFS allows for customizable bonding locations to hold the layer's internal registration during the lamination process.

Operators will use an FR4 template to lay up the layers thus eliminating the need for custom made tooling and lamination plates. Once layed up the machine will tack bond the internal locations.

Internal bond points removes the need for internal pinning.



The MFS is designed with manufacturers in mind:

- The central bonding station allows bonding locations to be placed along the outside border and/or in the image area
- An open work table allows for a wide range of panel sizes, thicknesses, and materials to be processed
- Simple PLC based controls allows for easy operation that fits into any manufacturing facility

BONDING

Bond Point Sizes (typical)

- 6mm (0.236") to 8mm (0.315")

Locations

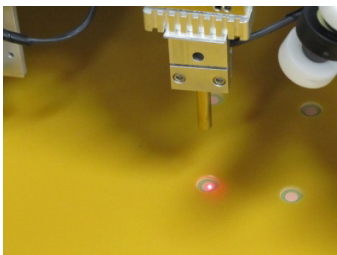
- Unlimited number of Bonding locations

The MFS can be equipped with four different bonding configurations:

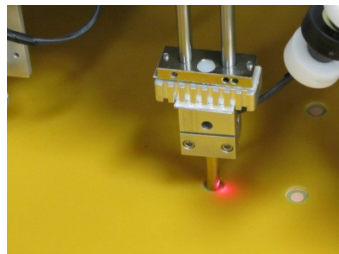
- Hot Heads
- Smart Weld™
- Combination
- Dual Head



Hot Head & Induction Combination Unit



Hot Head Unit



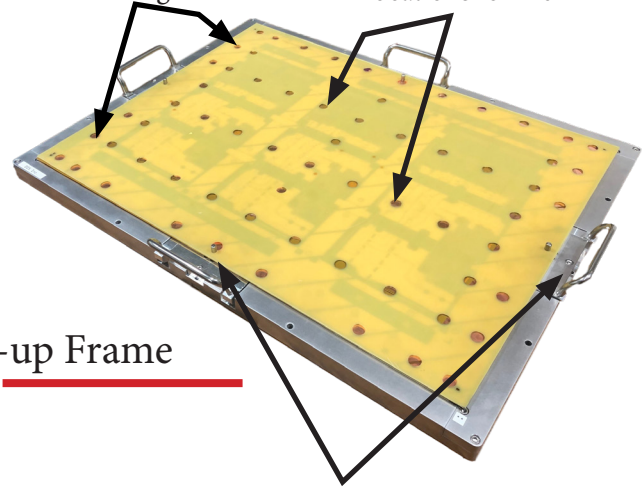
Learn more at:



SmartWeld™ is DIS's patented induction welding system. It consists of an upper and lower weld head. The complete weld cycle is controlled similar to a lamination press cycle. This allows rapid and precise heat control throughout the welding cycle giving more control to the process engineer. Each weld station is independently controlled.

External bonding locations for Rigid

Internal bonding locations for Flex



Lay-up Frame

Shown: 4-Slot pin tooling
- Or -

Can be used in conjunction with DIS FLX system

Dual Head Unit



This unit is set up to bond two panels simultaneously with the used of either dual Hot Heads or Induction heads.

